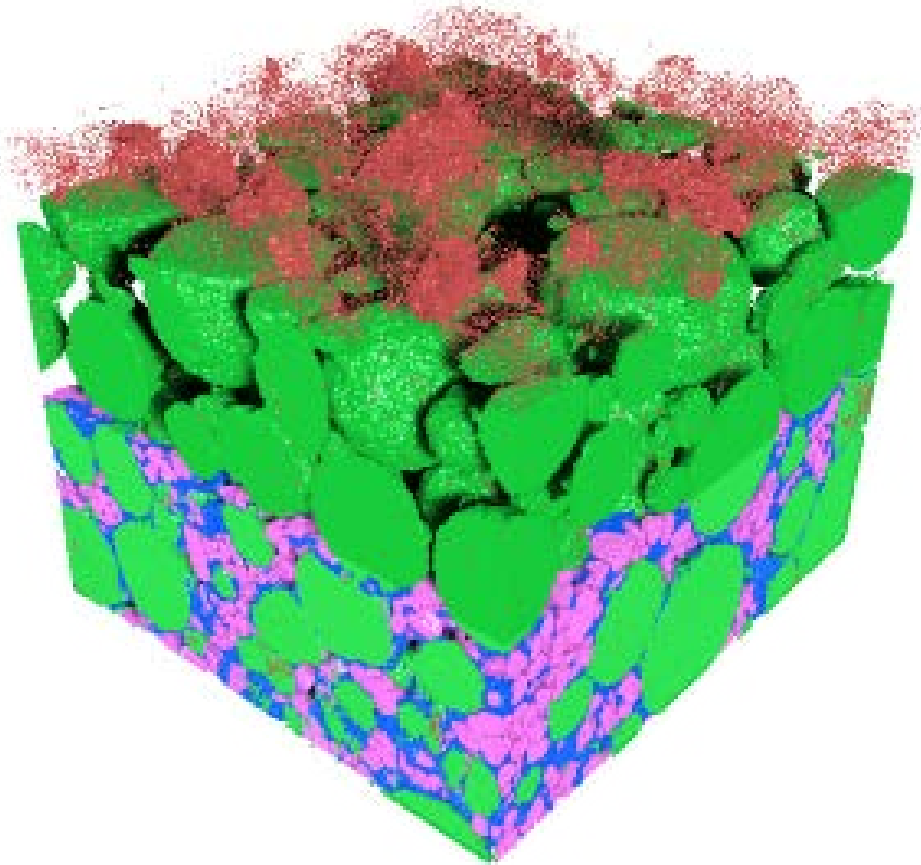
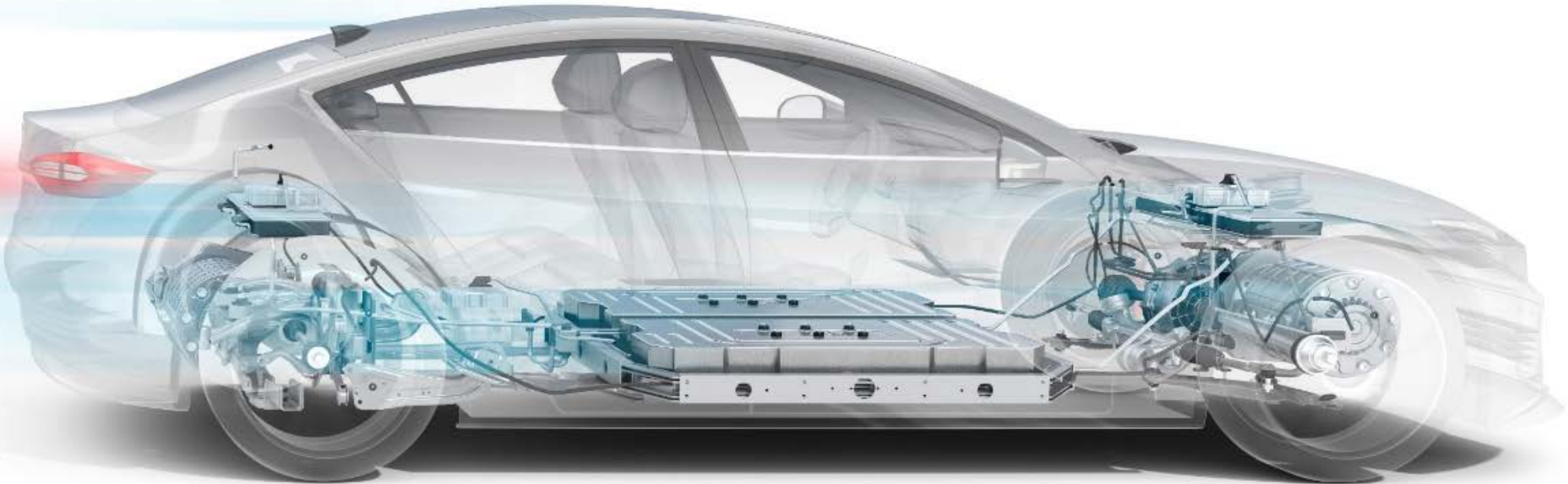


ZEISS eMobility Solutions



Seeing beyond

Battery Material High Resolution 3D Imaging by FIB



ZEISS eMobility Solutions

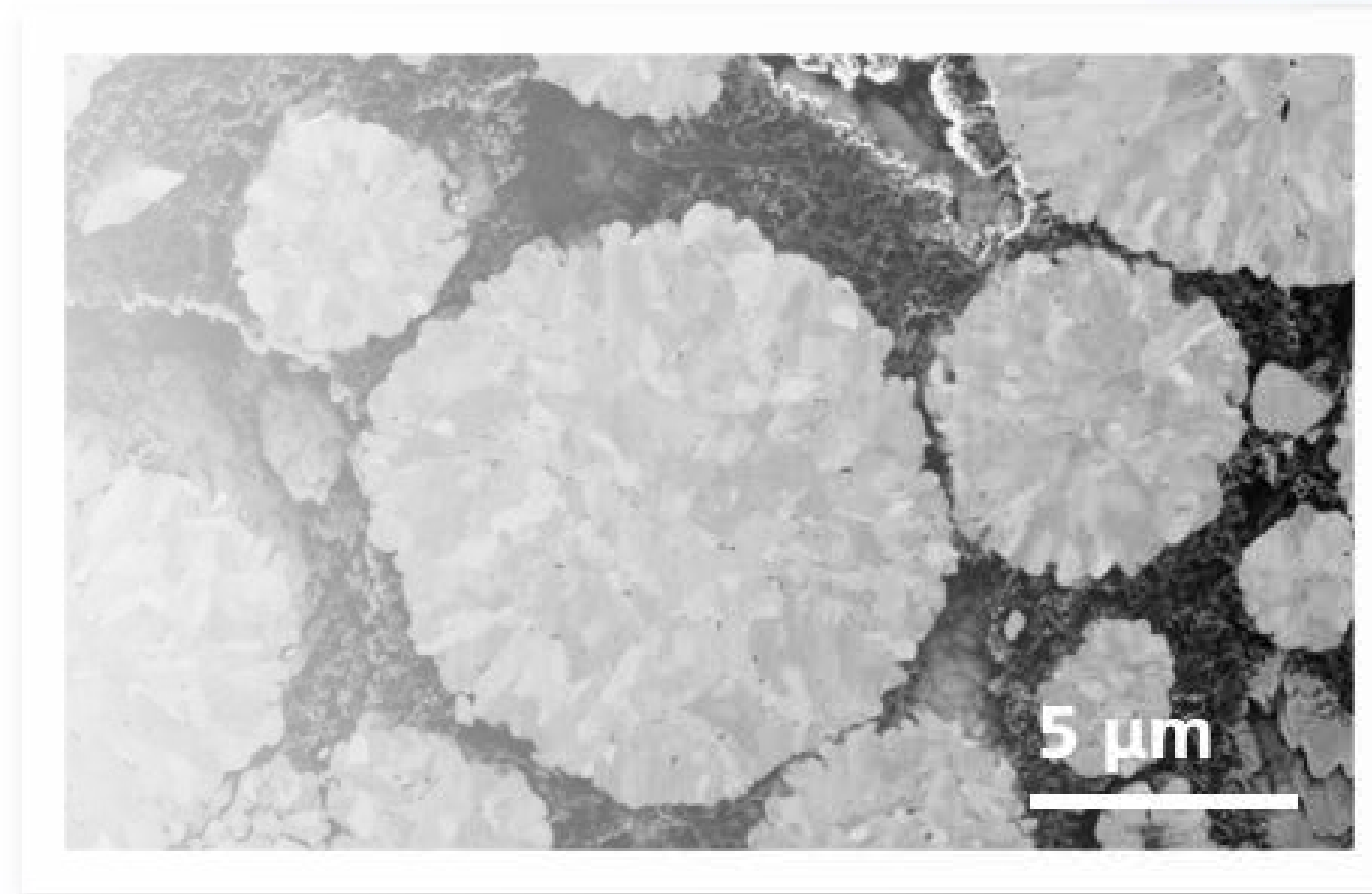
Battery Material High Resolution 3D Imaging by FIB

Powerful imaging & superior processing ability

High throughput 3D analysis and sample preparation

Power battery is a crucial component of new energy vehicles (NEV), directly impacting the safety, performance, and production costs of the entire vehicle. Comprising primarily of cathode and anode materials, separators, electrolytes, the development direction of batteries primarily revolves around the exploration of cathode and anode materials that offer high specific capacity, superior safety, low cost, and environmental friendliness.

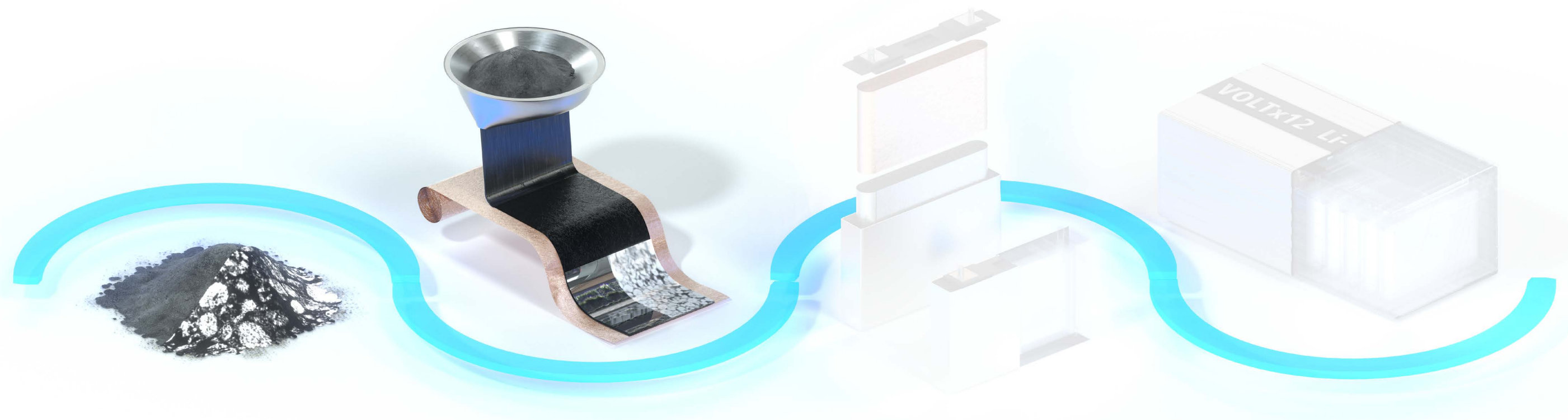
To develop new-generation battery materials, a series of characterizations and analyses must be conducted throughout the research and development (R&D) process. ZEISS provides Focused Ion Beam-Scanning Electron Microscope (FIB-SEM) as research tools for battery microstructure analysis.



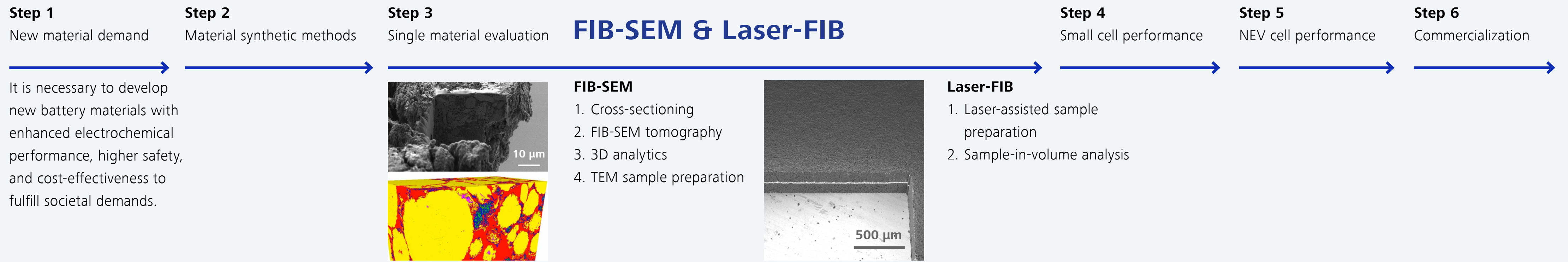
In-depth explore 3D structures

Evaluation with FIB-SEM & Laser-FIB

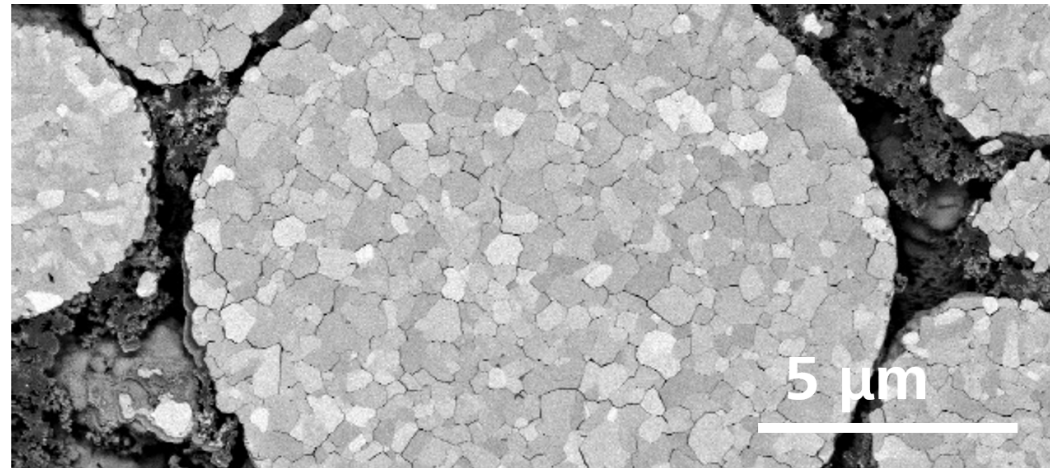
The battery production process encompasses material R&D, the electrode manufacturing, cell assembly, and module packaging. Among these steps, the quality of battery materials, including three-dimensional (3D) structure of materials, pore connectivity and other structural characteristics, is directly linked to the overall vehicle performance and safety. We can utilize the high-resolution FIB method to first obtain two-dimensional (2D) continuous slices of battery materials, and conduct 3D reconstruction to acquire the 3D volume data of the materials. In addition, femtosecond laser FIB can also help us quickly cut the specific area, significantly improving the efficiency of sample preparation.



R&D and production process evolution of NEV battery

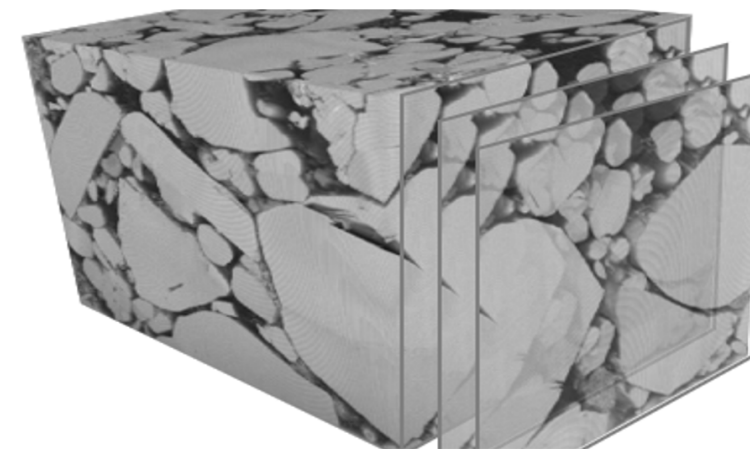


Application areas of FIB



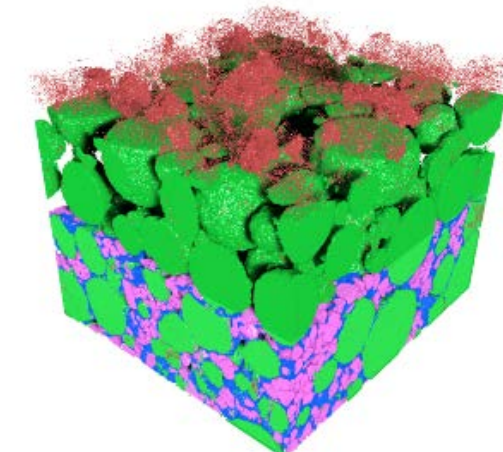
Cross-sectioning

- Acquire high resolution images of cross-sections to obtain sub-surface information



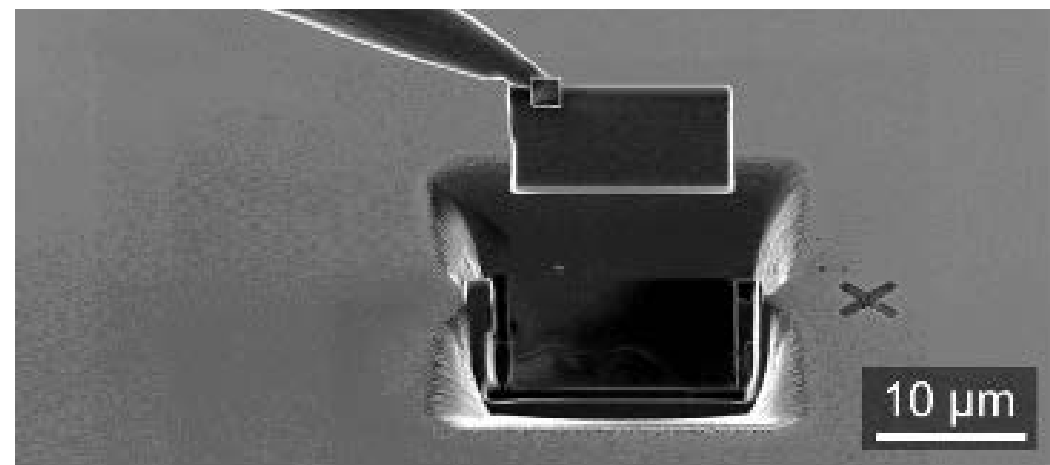
FIB-SEM tomography

- Perform serial cross-sectioning to image and reconstruct volumes of the sample



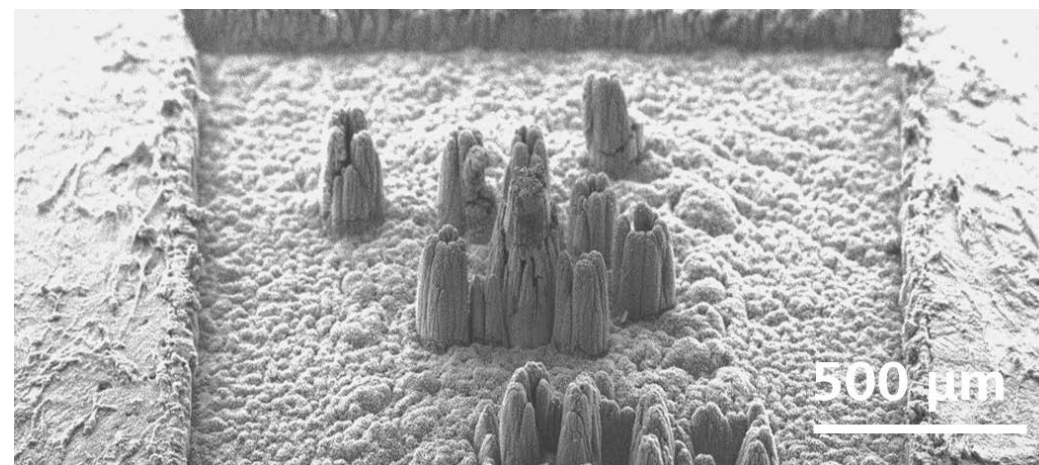
3D analytics

- Study the chemical and crystallographic microstructure of the sample



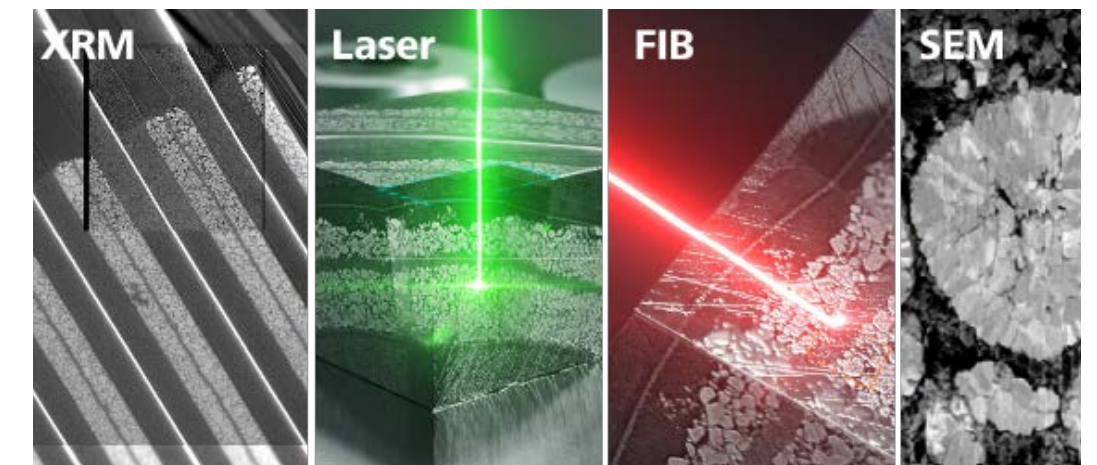
TEM sample preparation

- Prepare thin lamellae for their analysis in TEM or STEM



Laser-assisted sample preparation

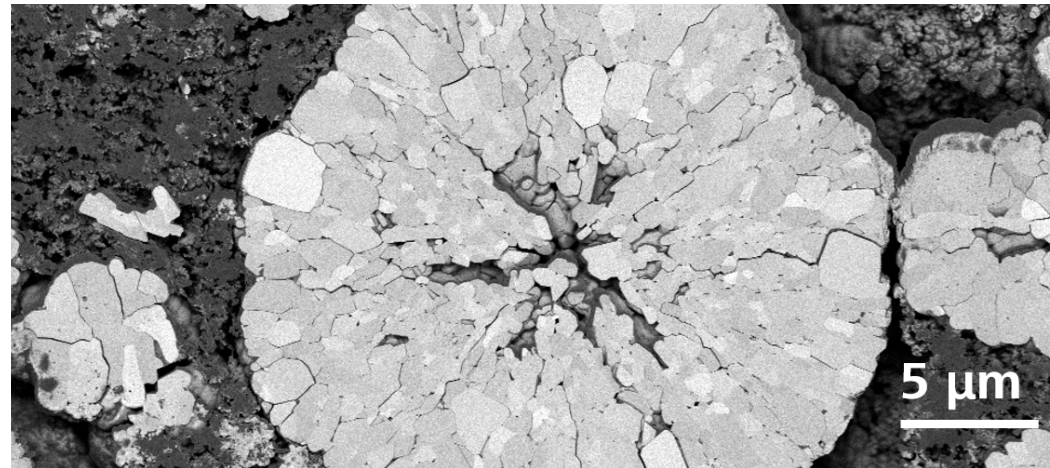
- Prepare large area samples rapidly with laser assistance



Sample-in-volume analysis

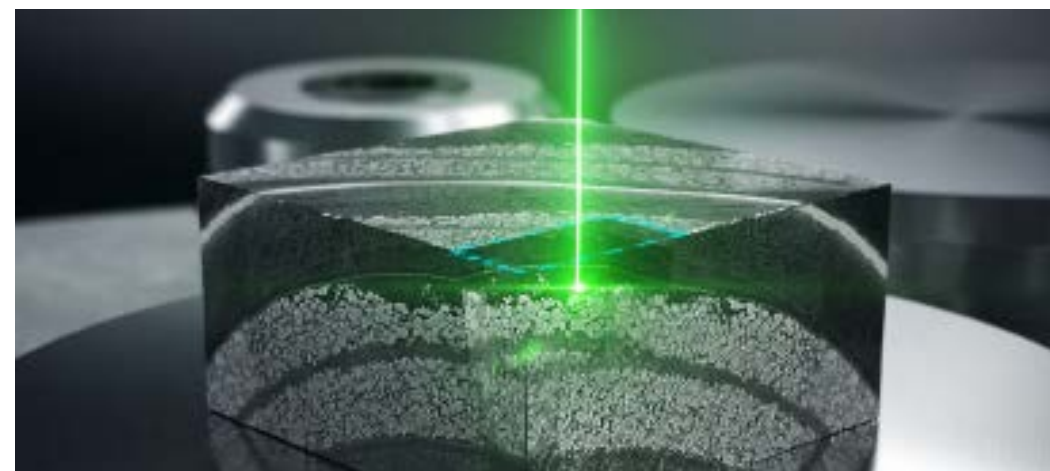
- Carry out multi-scale correlative workflow: 3D X-Ray microscope (XRM) and laser-FIB correlation

Value proposition of ZEISS solution



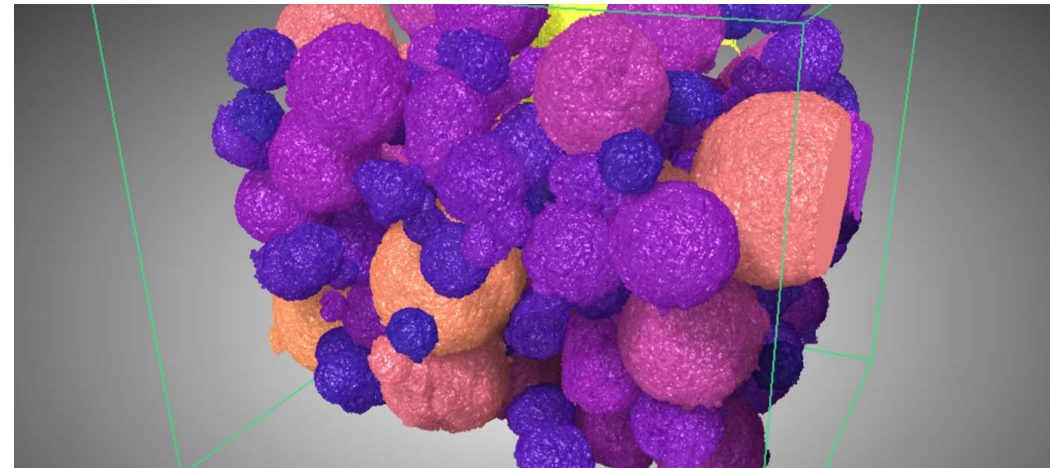
Excellent imaging results

- High imaging resolution and signal-to-noise ratio up to very low accelerating voltages
- Trackable voxel sizes and automated routines for active control of image quality



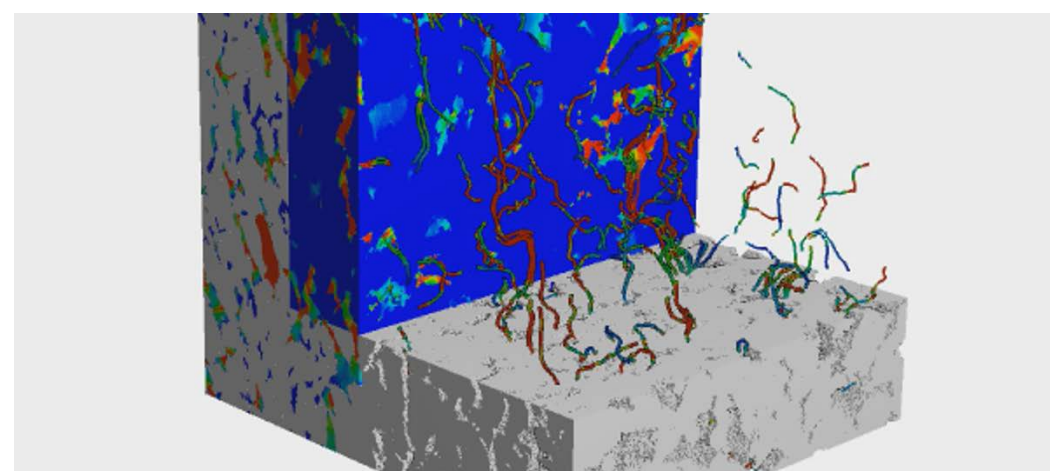
High R&D efficiency

- One-step research progress via site-specific sample preparation
- Time-saving large-volume removal via fs-laser



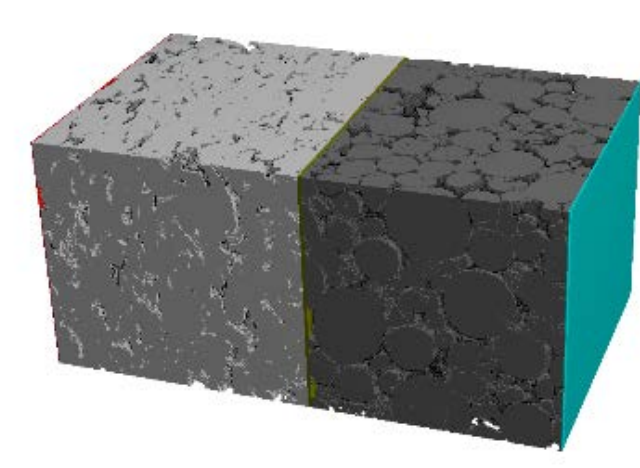
Best 3D resolution

- Best 3D resolution and leading isotropic voxel size
- Enable probe and image less than 3 nm in depth



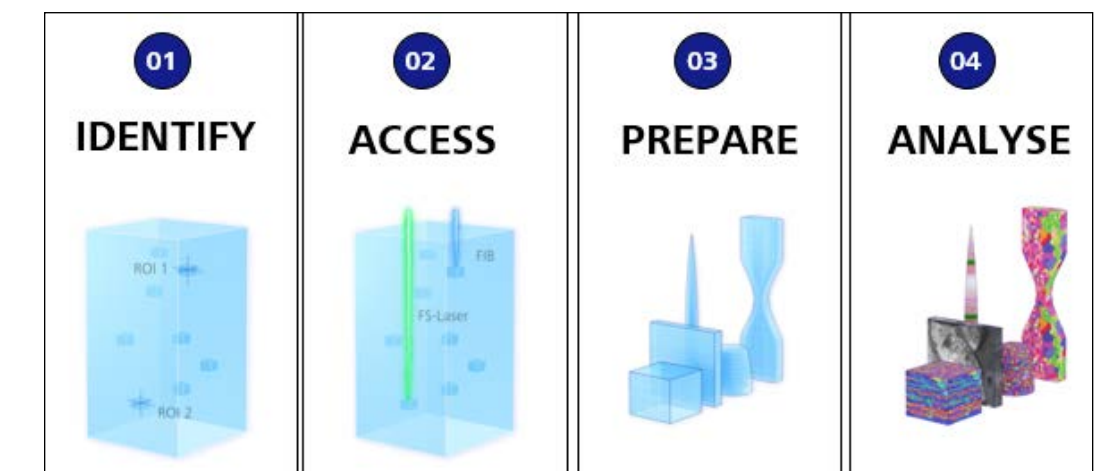
Intuitive & visual data

- Visualization of 2D and 3D data & simulation analysis results
- Mature analysis and statistics workflow



High accuracy

- Precise and reliable results in FIB-SEM tomography
- High repeatability of imaging and material study



Mature multi-scale correlative workflow

- Accurately identify and access a region of interest
- Prepare high-quality observation area and conduct analysis

Recommended portfolio

FIB-SEM for high-throughput 3D analysis and sample preparation

ZEISS Crossbeam

Resolution	3 nm @ 30 kV 120 nm @ 1 kV
Magnification	300x to 500,000x
Probe current	1 pA to 100 nA
Current stability	Stable over extended periods Automated emission recovery
Acceleration voltage	500 V to 30 kV



Benefits: ✓

- Best imaging and highest throughput
- High resolution 3D tomography and analytics
- Easy correlation of XRM/FIB/SEM/LM data

Access the battery inner structure withing seconds

ZEISS Crossbeam Laser

Wavelength (λ)	515 nm (green)
Ablation rate	>15 Mio. $\mu\text{m}^3/\text{s}$ (>0.9 mm^3/min) for Silicon
Focal length	100 mm (telecentric)
Pulse duration	< 350 fs
Safety	Laser class 1
Pulse repetition rate	0.1 kHz to 1 MHz
Average laser power	10 W @ 1 MHz
Focus diameter	< 15 μm
Rayleigh length	150 μm
Focus tracking length	6 mm (± 3 mm)
Scan field	40 x 40 mm^2



Benefits: ✓

- Fast and precise access to deeply buried structures
- Artefact free imaging without contamination
- Easy sample shuttling under Ar atmosphere or vacuum

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Sales & Service
Organizations

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Quality
Excellence
Centers

11

Locations

245

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Worldwide

Global Metrology Network

Our global service network provides easy access to ZEISS expertise around the world. We use local teams to ensure a swift response and reduced downtime. Make your operations even more secure and reliable with ZEISS.

Find your perfect solution today.
Contact our global experts.

